

6/15/17  
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**Avram Bar-Cohen, PhD**  
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**Biography:** Dr. Avram Bar-Cohen is an internationally recognized leader in thermal science and technology, an Honorary Member of ASME and Life Fellow of IEEE, currently serving as a Principal Engineering Fellow at Raytheon Corporation – Space and Airborne Systems, on leave from the University of Maryland. His publications, lectures, short courses, and research, as well as his US government and Professional service in ASME and IEEE, have helped to create the scientific foundation for the thermal management of electronic components and systems. His current efforts focus on embedded cooling, including on-chip thermoelectrics, diamond substrates, and two-phase microchannel coolers for high heat flux electronic and photonic components in computational, radar, and directed energy systems.

Bar-Cohen is a former Editor-in-Chief of the IEEE CPMT Transactions and serves on the Board of Governors of the CPMT Society. He has represented the Society as a Distinguished Lecturer for more than 15 years and is the President-elect of the CPMT Society. He recently completed his service as a Program Manager in the Microsystem Technology Office at the Defense Advanced Projects Agency in Virginia and had earlier served as Department Chair of Mechanical Engineering and Distinguished University Professor at the University of Maryland – College Park.

In 2014 Bar-Cohen was honored by the IEEE with the prestigious CPMT Field Award and had earlier been recognized with the CPMT Society's Outstanding Sustained Technical Contributions Award (2002). Among other awards, Bar-Cohen received the Luikov Medal from the International Center for Heat and Mass Transfer in Turkey (2008) and ASME's Heat Transfer Memorial Award (1999), Edwin F. Church Medal (1994), and Worcester Reed Warner Medal (1990).

In addition to serving as the Editor-in-Chief of WSPC's Encyclopedia of Thermal Packaging and the co-editor of the *Advanced Integration and Packaging* book series, Bar-Cohen has co-authored Dielectric Liquid Cooling of Immersed Components (WSPC, 2013), Design and Analysis of Heat Sinks (Wiley, 1995), and Thermal Analysis and Control of Electronic Equipment (McGraw-Hill, 1983), and has edited/co-edited 28 other books in this field. He has authored/co-authored more than 400 journal papers, refereed proceedings papers, and chapters in books and has delivered some 100 keynote, plenary and invited lectures at major Conferences, Symposia, and college campuses throughout the world.